



BOSTIK

**BORN²
BOND™**

Engineering Adhesives for Consumer Electronics



Adhesive solutions by
ARKEMA

Engineering Adhesives



BOSTIK

BORN²BOND™

Engineering Adhesives for Consumer Electronics

MANUFACTURING REQUIREMENTS

Bostik Born²Bond™ Engineering Adhesives enable manufacturers of consumer electronics to design and produce reliable, high-performance products that are easy to repair, maintain and recycle.

- Automation, in-line integration & high throughput
- Serviceability & repairability
- High precision, aesthetics & multi-substrates
- Sustainability & safety

SMARTWATCH ASSEMBLY

1 CASING AND PARTS ASSEMBLY

SOLUTIONS: Born²Bond™ High Performance HMPUR Adhesives

BENEFITS: Reliable bonding with HMPUR

2 ELECTRONICS ENCAPSULATION

SOLUTIONS: Born²Bond™ UV Epoxy Adhesives, UV-Instant Adhesives, UV-Acrylic Adhesives

BENEFITS: Durable encapsulation and protection; fast curing

3 SEALING AND GASKETING

SOLUTIONS: Born²Bond™ UV-CIPG Gasketing, UV-Acrylic Adhesives

BENEFITS: Serviceable gasketing with UV-CIPG; highly durable

4 BATTERY CELL ASSEMBLY

SOLUTIONS: Born²Bond™ UV Instant Adhesives, Instant Adhesives, Thermelt® Low Pressure Bio-Based Molding Hotmelt

BENEFITS: High-precision assembly; molding options for media resistance



5 PCB ASSEMBLY

SOLUTIONS: Born²Bond™ UV Instant Adhesives, Thermelt® Low Pressure Bio-Based Molding Hotmelt

BENEFITS: Durability; encapsulation and protection; fast curing; molding options

Explore Bostik's full range of electronics assembly and bonding solutions
[Born²Bond.Bostik.com/electronics](https://Born2Bond.Bostik.com/electronics)



Scan QR code
to watch video



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VR HEADSET ASSEMBLY

1 MICROPHONE AND SPEAKER MANUFACTURING AND ASSEMBLY

SOLUTIONS: Born2Bond™ High Performance HMPUR Adhesives

BENEFITS: Reliable bonding with HMPUR

3 THREADLOCKING OF SCREWS

SOLUTIONS: Born2Bond™ Anaerobic Adhesives

BENEFITS: Vibration, corrosion & chemical resistance; non-CLP WL range

5 OPTICAL SENSOR ENCAPSULATION AND BONDING

SOLUTIONS: Born2Bond™ UV Instant Adhesives, UV-Epoxy Adhesives, UV-Acrylic Adhesives

BENEFITS: Durability; encapsulation and protection; fast curing

2 FRONT COVER TO FRAME BONDING

SOLUTIONS: Born2Bond™ UV-CIPG Gasketing, High Performance HMPUR Adhesives

BENEFITS: Reliable bonding with HMPUR; serviceable gasketing with UV-CIPG

4 ELECTRONICS ENCAPSULATION AND PCB ASSEMBLY

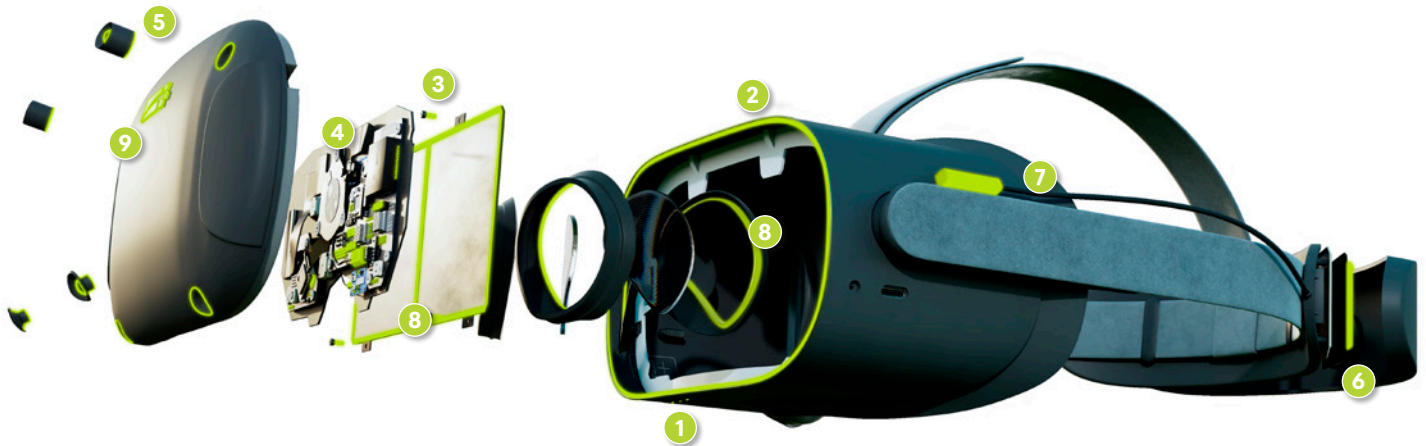
SOLUTIONS: Born2Bond™ UV-Epoxy Adhesives, UV Instant Adhesives, UV-Acrylic Adhesives, Thermelt® Low Pressure Bio-Based Molding Hotmelt

BENEFITS: Durable encapsulation and protection; fast curing; molding options

6 BATTERY AND ACOUSTIC ASSEMBLY

SOLUTIONS: Born2Bond™ UV-Epoxy Adhesives, UV-Acrylic Adhesives, Thermelt® Low Pressure Bio-Based Molding Hotmelt

BENEFITS: High strength and precision assembly; molding options for media resistance



7 CONNECTOR AND CABLE OVERMOLDING

SOLUTIONS: Thermelt® Low Pressure Bio-Based Molding Hotmelt

BENEFITS: Molding options for media resistance

9 DECORATION AND LOGO BONDING

SOLUTIONS: Born2Bond™ UV Instant Adhesives

BENEFITS: Fast curing

8 LENS AND DISPLAY BONDING

SOLUTIONS: Born2Bond™ UV-Epoxy Adhesives, UV-Acrylic Adhesives

BENEFITS: High strength and precision assembly



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LAPTOP ASSEMBLY

1 ENCLOSURE ASSEMBLY

SOLUTIONS: Born2Bond™ UV-CIPG Gasketing (serviceable), High Performance HMPUR Adhesives (non-serviceable), Instant Adhesives, 2K MMA

BENEFITS: Reliable bonding with HMPUR; serviceable gasketing with UV-CIPG; multi-substrates

2 BATTERY CELL ASSEMBLY

SOLUTIONS: Born2Bond™ UV Instant Adhesives, Instant Adhesives, Thermelt® Low Pressure Bio-Based Molding Hotmelt

BENEFITS: High-precision assembly; molding options for media resistance

3 ELECTRONICS ENCAPSULATION

SOLUTIONS: Born2Bond™ UV Epoxy Adhesives, UV-Instant Adhesives, UV-Acrylic Adhesives

BENEFITS: Durable encapsulation and protection; fast curing

4 THREADLOCKING OF SCREWS

SOLUTIONS: Born2Bond™ Anaerobic Adhesives

BENEFITS: Vibration, corrosion & chemical resistance; non-CLP WL range

5 PCB ASSEMBLY

SOLUTIONS: Born2Bond™ UV Instant Adhesives, Thermelt® Low Pressure Bio-Based Molding Hotmelt

BENEFITS: Durability; encapsulation and protection; fast curing; molding options



6 DISPLAY PANEL BONDING

SOLUTIONS: Born2Bond™ UV-CIPG Gasketing (serviceable), High Performance HMPUR Adhesives (non-serviceable)

BENEFITS: Reliable bonding with HMPUR; serviceable gasketing with UV-CIPG; multi-substrates

7 TOUCHPAD ASSEMBLY

SOLUTIONS: Born2Bond™ UV Epoxy Adhesives, UV Instant Adhesives, UV-Acrylic Adhesives

BENEFITS: High strength and protection; fast curing

8 PLASTIC PARTS ASSEMBLY

SOLUTIONS: Born2Bond™ UV Instant Adhesives, Instant Adhesives

BENEFITS: Low blooming; fast curing

9 SPEAKER ASSEMBLY

SOLUTIONS: Born2Bond™ High Performance HMPUR Adhesives, Instant Adhesives, UV-Acrylic Adhesives

BENEFITS: Reliable bonding with HMPUR; fast curing



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SMARTPHONE ASSEMBLY

1 THREADLOCKING OF SCREWS

SOLUTIONS: Born2Bond™ Anaerobic Adhesives

BENEFITS: Vibration, corrosion & chemical resistance; non-CLP WL range

3 PCB ASSEMBLY

SOLUTIONS: Born2Bond™ UV Instant Adhesives, Thermelt® Low Pressure Bio-Based Molding Hotmelt

BENEFITS: Durability; encapsulation and protection; fast curing; molding options

2 ELECTRONICS ENCAPSULATION

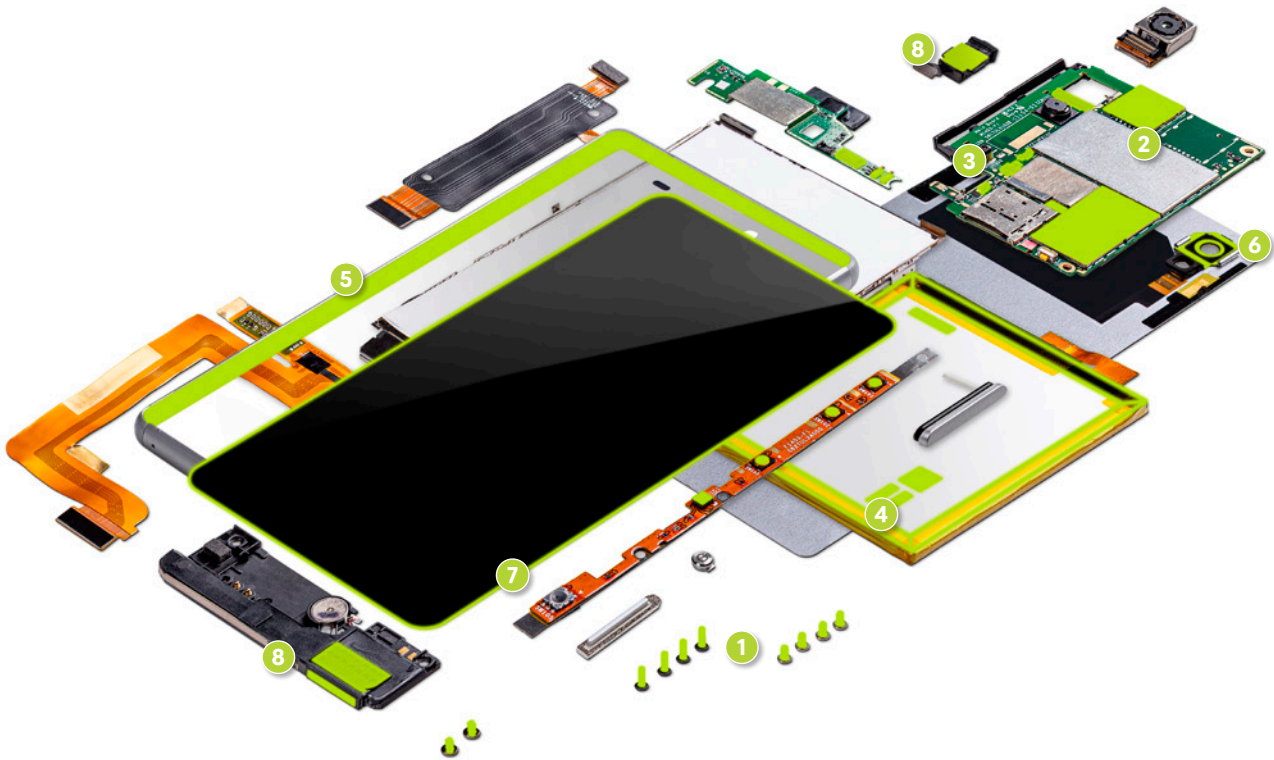
SOLUTIONS: Born2Bond™ UV Epoxy Adhesives, UV-Instant Adhesives, UV-Acrylic Adhesives

BENEFITS: Durable encapsulation and protection; fast curing

4 BATTERY CELL ASSEMBLY

SOLUTIONS: Born2Bond™ UV Instant Adhesives, Instant Adhesives, Thermelt® Low Pressure Bio-Based Molding Hotmelt

BENEFITS: High-precision assembly; molding options for media resistance



5 ENCLOSURE ASSEMBLY

SOLUTIONS: Born2Bond™ High Performance HMPUR Adhesives (non-serviceable), Instant Adhesives

BENEFITS: Reliable bonding with HMPUR; multi-substrates

7 DISPLAY/TOUCH PANEL BONDING

SOLUTIONS: Born2Bond™ High Performance HMPUR Adhesives (non-serviceable)

BENEFITS: Reliable bonding with HMPUR; multi-substrates

6 CAMERA MODULE ASSEMBLY

SOLUTIONS: Born2Bond™ High Performance HMPUR Adhesives, UV Instant Adhesives, UV-Acrylic Adhesives

BENEFITS: Reliable bonding with HMPUR; durable encapsulation and protection; fast curing

8 ACOUSTIC ASSEMBLY

SOLUTIONS: Born2Bond™ High Performance HMPUR Adhesives, UV-Acrylic Adhesives

BENEFITS: Reliable bonding with HMPUR



BORN²BOND™

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BORN²BOND™ SOLUTIONS

All **Born²Bond™ Engineering Adhesives** are suitable for small production runs using manual application, as well as semi- or fully-automated production lines.

BORN²BOND™ INSTANT and UV-INSTANT ADHESIVES

- Low odor and low bloom solutions available for increased user comfort and uncompromised fine finishes
- Dual-cure adhesives feature 'cure-on-demand' properties for increased throughput and cure of excess material (patented **Light Lock** grades only*)
- Fast bonding solutions available for enhanced reliability and durability
- Automatic, semi-automatic and manual high-precision dispensing options



BORN²BOND™ UV-EPOXY and UV-ACRYLIC ADHESIVES

- Highly durable - impact, chemical and temperature resistant
- Multi-substrate adhesion to metals, glass and plastics (including ABS and PMMA)
- Suitable for high precision and high-speed automated dispensing using a wide variety of equipment and methods
- Wide UV wavelength range
- Available in multiple viscosities



BORN²BOND™ HIGH PERFORMANCE HMPUR ADHESIVES

- Multi-substrate adhesion
- High temperature, humidity and chemical resistance
- Good balance between strength and elasticity
- Designed for manual, semi-automatic and automated dispensing for high-precision applications
- Extensive range, with tailor-made solutions available



BORN²BOND™ UV-CIPG GASKETING

- Serviceability of assembled and sealed parts and enclosures
- Waterproofing and dustproofing for increased durability
- Resistant to chemicals and temperature fluctuations
- Extremely flexible and durable
- Designed for semi-automatic and automated dispensing for high-precision applications



HIGH PERFORMANCE POLYMERS

ARKEMA

Beyond Bostik's portfolio as the adhesive solutions division, Arkema also offers pioneering high-performance polymers from renewable sources to customers from a broad range of markets. Bio-based and recyclable **Rilsan® Polyamide 11** is chosen by manufacturers for its lightweight properties, flexibility or high rigidity when required, good UV resistance, overall durability as well as easy processibility. **Piezotech® electroactive polymers** for organic, printed and flexible electronics make it possible to design the next generation of sensors, speakers, haptic devices and more – making them ideal for consumer electronics applications.



For more information and to order free **Born²Bond™** samples, please visit: Born2Bond.Bostik.com



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